Response to Office Action of 06/27/2006

REMARKS

Upon entry of this amendment, claims 1-4 and 6-10 will be pending.

The Applicants appreciate the Examiner's continued attention and consideration.

Claims 1 - 4 and 6 - 10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Polinski, Sr. (U.S. 5,386,339).

Independent claim 1 has been amended to recite: "A circuit board assembly comprising: a co-fired substrate comprising at least first and second regions superimposed and bonded to each other, and the first region being formed of a plurality of superimposed first layers, ... the second region being formed of at least one second layer ...; and a surface-mount IC device mounted to a first surface of the substrate defined by one of the first ceramic layers, wherein the first and second regions are arranged for serial thermal interconnection between sand IC device and on opposed heat sink, and wherein each first ceramic layer and said at least one second ceramic layer have substantially similar width and length characteristic dimensions.".

The Polinski device discloses low thermal conductivity sheets which are segmented and do not extend laterally and longitudinally coextensively with the high thermal conductivity sheets. Figure 5 illustrates (laterally) alternating low thermal conductivity sheets 122 and high thermal conductivity sheets 126. The high thermal conductivity sheets constitute the heat sink 128.

10

USSN 10/709.209 filed 04/21/2004 (DP-305691)

Amendment dated: 01-NOV-2006

Response to Office Action of 06/27/2006

In the present invention, the overlaying non-conductive layers 36 and underlying conductive layer(s) 34 provide distinct continuous regions which are disposed in series between the power chip 12 and the heat sink 20 and extend laterally and longitudinally to

common edges or coextensive end limits.

Accordingly, in view of the amendments, claim 1 clearly distinguishes over Polinski

Claims 3 – 4 and 6 – 9 depend from independent claim 1 and are deemed to distinguish

over Polinski for the reasons set forth hereinabove.

Independent claim 10 was similarly amended to recite: "A circuit board assembly

comprising: ... wherein each first ceramic layer and said at least one second ceramic

layer have substantially similar width and length characteristic dimensions."

The specified lateral and longitudinal equal dimensioning and coextensive end limits or

registration of the edges of the layers is clearly depicted in Figure 4.

Accordingly, claim 10, as amended, also clearly distinguishes over Polinski.

11

USSN 10/709,209 filed 04/21/2004 (DP-305691)

Amendment dated: 01-NOV-2006

Response to Office Action of 06/27/2006

Conclusion

Applicant believes, in view of the amendments and remarks herein, that all grounds of

rejection of the claims have been addressed and overcome, and that all claims are in

condition for allowance.

If it would further prosecution of the application, the Examiner is urged to contact the

undersigned at the telephone number provided.

The Commissioner is hereby authorized to charge any fees associated with this

communication and/or credit any overpayments to Deposit Account No. 50-0831.

Respectfully submitted,

J. GORDON LEWIS

Reg. No.: 28,735

(248) 813-1234

Dated: 01-NOV-2006

12